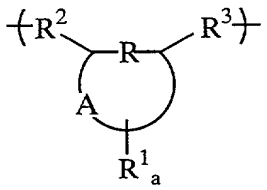
CLAIMS:

1. A polymer comprising recurring units of the following general formula (1):



(1)

wherein A is a divalent aliphatic or alicyclic hydrocarbon group of 2 to 20 carbon atoms, R^1 is an alkyl group containing at least one fluorine atom, which may contain a hetero atom such as oxygen, nitrogen or sulfur to form an ether, ester, carbonate, alcohol, acetoxy or thioester, "a" is a positive number of 1 to 3, R is a single bond, methylene group, oxygen atom, NH group or sulfur atom, and R^2 and R^3 each are a single bond or methylene group.

2. The polymer of claim 1 further comprising recurring units containing acid labile groups.

3. A chemically amplified resist composition comprising the polymer of claim 1 or 2.

4. A chemically amplified positive resist composition comprising

(A) the polymer of claim 1 or 2,

(B) an organic solvent, and

(C) a photoacid generator.

5. The resist composition of claim 4 further comprising a basic compound.

6. The resist composition of claim 4 further comprising a dissolution inhibitor.

7. A process for forming a resist pattern comprising the steps of:

applying the resist composition of claim 4 onto a substrate to form a coating,

heat treating the coating and then exposing it to high-energy radiation having a wavelength of up to 180 nm or electron beams through a photo mask, and

optionally heat treating the exposed coating and developing it with a developer.